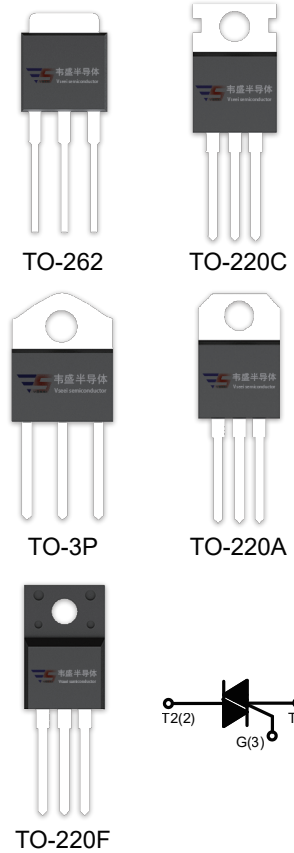


## DESCRIPTION:

With high ability to withstand the shock loading of large current, BTB24-600CW series triacs provide high dv/dt rate with strong resistance to electromagnetic interface. With high commutation performances, 3 quadrants products especially recommended for use on inductive load.



## MAIN FEATURES

Symbol	Value	Unit
$I_{T(RMS)}$	25	A
$V_{DRM}/V_{RRM}$	600/800/1200/1600	V

## ABSOLUTE MAXIMUM RATINGS

Parameter		Symbol	Value	Unit
Storage junction temperature range		$T_{stg}$	-40-150	°C
Operating junction temperature range		$T_j$	-40-125	°C
Repetitive peak off-state voltage ( $T_j=25^{\circ}C$ )		$V_{DRM}$	600/800/1200/1600	V
Repetitive peak reverse voltage ( $T_j=25^{\circ}C$ )		$V_{RRM}$	600/800/1200/1600	V
RMS on-state current	TO-220A(Ins)/ TO-220F(Ins) ( $T_c=70^{\circ}C$ )	$I_{T(RMS)}$	25	A
	TO-220C/ TO-220A(Non-Ins) ( $T_c=85^{\circ}C$ )			
	TO-262 ( $T_c=50^{\circ}C$ )			
	TO-3P(Ins) ( $T_c=95^{\circ}C$ )			
Non repetitive surge peak on-state current (full cycle, $F=50Hz$ )		$I_{TSM}$	250	A
$I^2t$ value for fusing ( $t_p=10ms$ )		$I^2t$	340	$A^2s$

Critical rate of rise of on-state current ( $I_G = 2 \times I_{GT}$ )	$di/dt$	50	A/ $\mu$ s
Peak gate current	$I_{GM}$	4	A
Average gate power dissipation	$P_{G(AV)}$	1	W
Peak gate power	$P_{GM}$	10	W

**ELECTRICAL CHARACTERISTICS** ( $T_j = 25^\circ\text{C}$  unless otherwise specified)

 $V_{DRM}/V_{RRM}$ : 600/800V

Symbol	Test Condition	Quadrant		JST24-600/800V		Unit
				BW	CW	
$I_{GT}$	$V_D = 12V$ $R_L = 33\Omega$	I - II - III	MAX	50	35	mA
$V_{GT}$		I - II - III	MAX	1.3		V
$V_{GD}$	$V_D = V_{DRM}$ $T_j = 125^\circ\text{C}$ $R_L = 3.3K\Omega$	I - II - III	MIN	0.2		V
$I_L$	$I_G = 1.2I_{GT}$	I - III	MAX	80	70	mA
		II		100	80	
$I_H$	$I_T = 100\text{mA}$		MAX	75	50	mA
$dV/dt$	$V_D = 2/3V_{DRM}$ Gate Open $T_j = 125^\circ\text{C}$		MIN	1000	500	V/ $\mu$ s

 $V_{DRM}/V_{RRM}$ : 1200/1600V

Symbol	Test Condition	Quadrant		JST24-1200V/1600V		Unit
				BW	CW	
$I_{GT}$	$V_D = 12V$ $R_L = 33\Omega$	I - II - III	MAX	50	35	mA
$V_{GT}$		I - II - III	MAX	1.5		V
$V_{GD}$	$V_D = V_{DRM}$ $T_j = 125^\circ\text{C}$ $R_L = 3.3K\Omega$	I - II - III	MIN	0.2		V
$I_L$	$I_G = 1.2I_{GT}$	I - III	MAX	90	70	mA
		II		100	80	
$I_H$	$I_T = 100\text{mA}$		MAX	80	60	mA
$dV/dt$	$V_D = 2/3V_{DRM}$ Gate Open $T_j = 125^\circ\text{C}$		MIN	1500	1000	V/ $\mu$ s

$V_{\text{DRM}}/V_{\text{RRM}}: 600/800\text{V}$ 

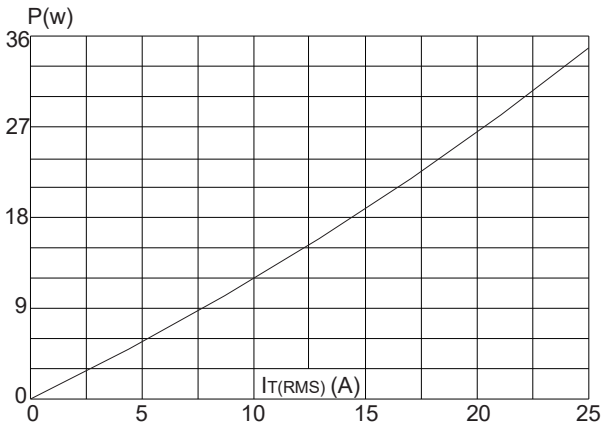
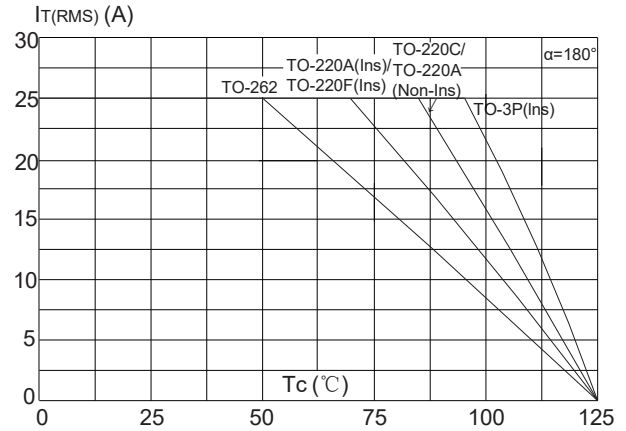
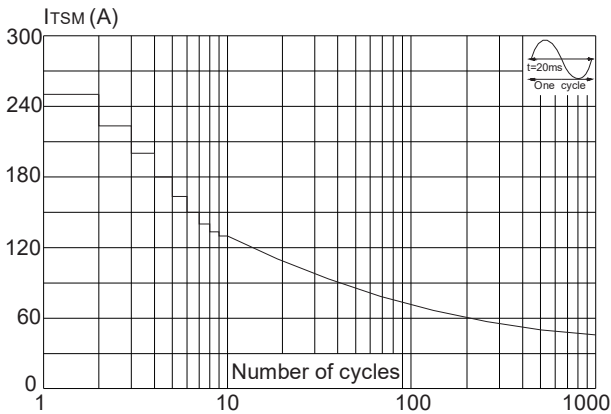
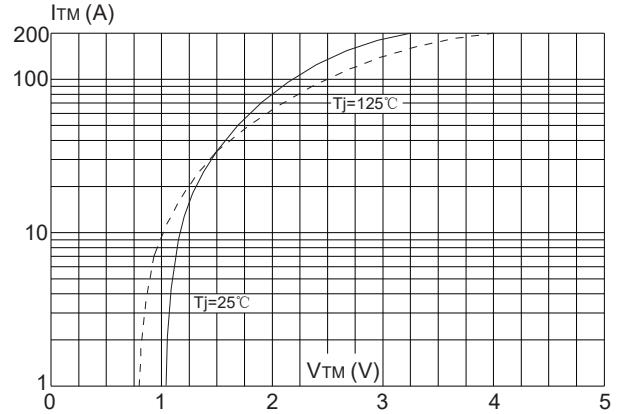
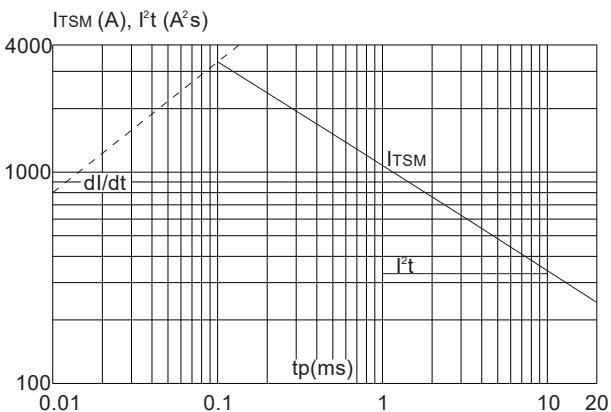
Symbol	Test Condition	Quadrant		JST24-600/800V		Unit
				B	C	
$I_{\text{GT}}$	$V_{\text{D}}=12\text{V } R_{\text{L}}=33\Omega$	I - II -III	MAX	50	25	mA
		IV		70	50	
$V_{\text{GT}}$		ALL	MAX	1.3		V
$V_{\text{GD}}$	$V_{\text{D}}=V_{\text{DRM}} T_{\text{J}}=125^{\circ}\text{C}$ $R_{\text{L}}=3.3\text{K}\Omega$	ALL	MIN	0.2		V
$I_{\text{L}}$	$I_{\text{G}}=1.2I_{\text{GT}}$	I -III-IV	MAX	80	70	mA
		II		100	90	
$I_{\text{H}}$	$I_{\text{T}}=100\text{mA}$		MAX	75	60	mA
$dV/dt$	$V_{\text{D}}=2/3V_{\text{DRM}}$ Gate Open $T_{\text{J}}=125^{\circ}\text{C}$		MIN	500	200	V/ $\mu\text{s}$

## STATIC CHARACTERISTICS

Symbol	Parameter		Value(MAX)	Unit
$V_{\text{TM}}$	$I_{\text{TM}}=35\text{A } t_{\text{p}}=380\mu\text{s}$	$T_{\text{J}}=25^{\circ}\text{C}$	1.5	V
$I_{\text{DRM}}$	$V_{\text{D}}=V_{\text{DRM}} V_{\text{R}}=V_{\text{RRM}}$	$T_{\text{J}}=25^{\circ}\text{C}$	5	$\mu\text{A}$
$I_{\text{RRM}}$		$T_{\text{J}}=125^{\circ}\text{C}$	3	mA

## THERMAL RESISTANCES

Symbol	Parameter		Value	Unit
$R_{\text{th(j-c)}}$	junction to case(AC)	TO-220A(Ins)	1.5	$^{\circ}\text{C/W}$
		TO-220C/ TO-220A(Non-Ins)	1.1	
		TO-220F(Ins)	1.7	
		TO-262	2.1	
		TO-3P(Ins)	0.67	

**FIG.1:** Maximum power dissipation versus RMS on-state current

**FIG.2:** RMS on-state current versus case temperature

**FIG.3:** Surge peak on-state current versus number of cycles

**FIG.4:** On-state characteristics (maximum values)

**FIG.5:** Non-repetitive surge peak on-state current for a sinusoidal pulse with width  $t_p < 20\text{ms}$ , and corresponding value of  $I^2t$  ( $di/dt < 50\text{A}/\mu\text{s}$ )

**FIG.6:** Relative variations of gate trigger current, holding current and latching current versus junction temperature
